



Docket No. 58102-DIV (71987)

THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: C. Huang

U.S. SERIAL NO.: 10/787,269 GROUP: 2814

FILED: February 25, 2004 EXAMINER: P. Cao

FOR: SEMICONDUCTOR PACKAGE WITH HEAT DISSIPATING
STRUCTURE

CERTIFICATE OF EXPRESS MAILING

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with the United States Postal Service on this date August 18, 2006 in an envelope as "Express Mail Post Office to Addressee," mailing Label Number EV755072377US addressed to the: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

By: Kathleen M. Drury
Kathleen M. Drury

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

AMENDMENT

Applicant is in receipt of the Office Action dated February 21, 2006 of the above-referenced application. A Request for Continued Examination (RCE) and a three-month extension of time are submitted herewith. Please amend the application as follows:

Amendments to the claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 7 of this paper.